SOLDER PASTE

BGA LEAD-FREE SOLDER PASTE

Sn42/Bi58

Melting point138°C



Product Usage

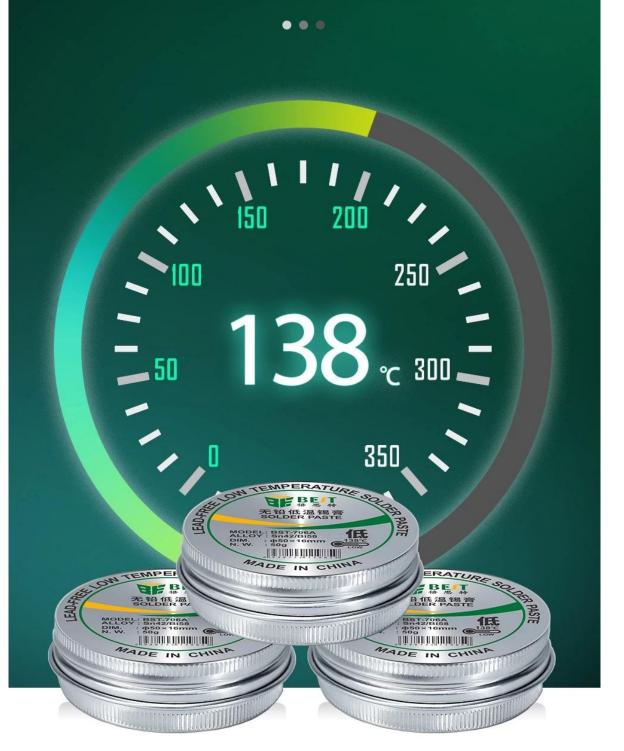
TIN PASTE

Model	BST-706
Name	Low temperature solder paste
Composition	Sn42/Bi58
Melting point	138℃
G.W.	50g
Granule	20~38μm
Size	φ50*16mm

Sn42/Bi58

Lead-free low temperature melting point

138°C





Welding requirements for a wide range of products SMT patch LED patch BGA welding

Product Size

